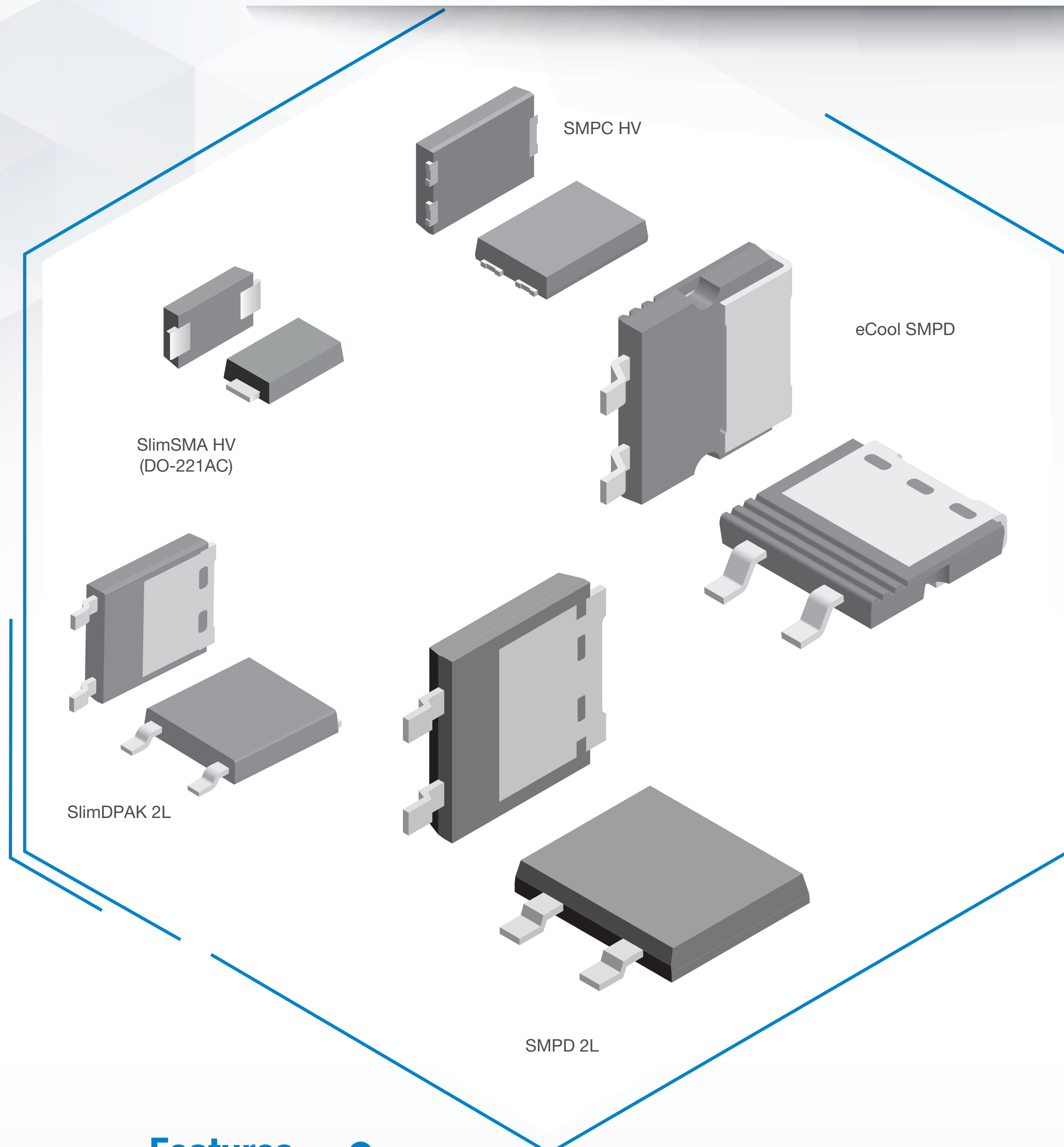




The DNA of tech.®

eSMP® Series

High Voltage Package Solutions for Rectifiers



● **eSMP® Packages** enhanced Surface-Mount Power packages

● Low profile and small footprint

● **Product technologies available in eSMP® series high voltage packages:**

- Standard recovery rectifiers
- FRED Pt® rectifiers
- Silicon carbide (SiC) Schottky rectifiers

Features

Enhanced Insulation

- Larger creepage distances
- High CTI mold compound for superior insulation

Customer Benefits

- Designed to provide safer high voltage applications
- Reduced diode count and optimized packaging drive ultra compact PCB designs and superior cost efficiency

Certification



**AEC-Q101
Qualified Available**

Applications

